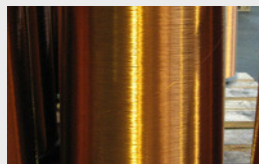


## SELF BONDABLE ROUND COPPER



HIGH TEMPERATURE	H180 TERMO	H180 TERMO
Thermal class	180°C	180°C
Nature of the isolation	<b>Base Coat:</b> Polyesterimide <b>Top Coat:</b> Aliphatic Polyamide	<b>Base Coat:</b> Polyesterimide <b>Top Coat:</b> Aromatic Polyamide
Diameter	Φ 0.18 - 2.00mm	Φ 0.18 - 2.00mm
Grade	G-1B and G-2B	G-1B and G-2B
Colour	Natural, Red, Green, Black	Natural, Red, Green, Black
Bonding temperature	170°C	210°C
Resoftening temperature	155°C	190°C
Breakdown voltage	≥ 1.5 x IEC	≥ 1.5 x IEC
Heat shock	> 175°C	> 175°C
Solderability	n.a.	n.a.
Cut through	≥ 300	≥ 300
Standard	IEC 60317-37 MW 3C IEC-851 (Testing methods)	IEC 60317-37 MW 3C IEC-851 (Testing methods)
Certifications	ISO TS 16949 ISO 9001:2000	ISO TS 16949 ISO 9001:2000
Description	Cu H180 TERMO "Diameter" G-"Grade"	Cu H180 TERMO "Diameter" G-"Grade"
Applications	Voice coils (e.g. receiver), small motors, RFID cards, tag coils, camera coils, optical pick up coils, spindle motors	Voice coils (e.g. receiver), small motors, RFID cards, tag coils, camera coils, optical pick up coils, spindle motors